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(54) FORMATION OF BUMP ELECTRODE

(57) Abstract:

PURPOSE: To improve reliability in the connection to a substrate by easily forming a nucleus of a bump electrode consisting of an elastic body in the central part of the bump electrode of an LSI chip.

CONSTITUTION: At the time of forming a bump electrode on a barrier metal 4 by plating, a plating mask 5 is formed of an elastic body and an opening part is made into the ring shape, plating is performed so as to cover a part of the plating mask remained in the center in order to obtain the bump electrode 8 having a nucleus of a plastic body. This is a method for easily forming a nucleus 6 of a bump electrode consisting of an elastic body in the central part of the bump electrode of an LSI chip.

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